In November 1995, CESC was officially established.

In September 1997, CESC brought in the world most sophistic contact IC card and contact IC card module packaging lines.

In February 1999, CESC gained the *IC Card Registration Certificate* issued by National Integrated Circuit Registration Center.

In December 1999, CESC passed ISO9002:1994 Quality Assurance System authentication.

In 2001, CESC undertook the national project of *Process and Technology Research on Mass Production of IC Card Chip Packaging* and finally obtained “Excellent Research Result” award due to its contribution in the State “9-5”Science and Technology Research Project.

In July 2001, CESC was designated as the SIM card manufacturer of China Mobile Communications Corporation (CMCC).

In April 2002, CESC obtained the *Industrial Product Manufacture License* for IC card issued by General Administration of Quality Supervision, Inspection and Quarantine of the PRC.

In July 2002, CESC moved to Changping Science and Technology Park in Beijing and built its professional factory complying with VISA and MASTER standards.

In 2003, CESC was designated as the professional IC card module manufacturer for the second generation of China national citizen ID card by Ministry of Information Industry and Ministry of Public Security and started the mass production.

In December 2003, CESC passed ISO9001:2000 Quality Management System authentication.

In 2004, CESC was awarded the title of *Top 10 Manufacturers in Smart Card Field*.

In November 2001, the yields of IC card and IC card module both passed 10 million and thus made CESC the largest IC card and IC card module manufacturer in domestic.

In 2005, CESC was again awarded the title of *Top 10 Manufacturers in Smart Card Field*.

In November 2005, CESC celebrated the tenth anniversary.

In February 2006, CESC passed ISO14001:2004 Environment Management System authentication.

In March 2007, CESC was awarded the title of *Top 10 Manufacturers in Smart Card Field* for the third time.

In January 2007, CESC won the award of 2006 China Smart Card Industry's First Brand in Quality and Reputation.

In March 2007, CESC won the award of 2005-2006 China Semiconductor Innovative Products.

In June 2007, CESC won the SMART Award of 2006 China smart card industry and the Most Welcomed Suppliers Award.

In May 2008, CESC obtained Humanitarian Service Medal issued by China Red Cross due to its charitable donation.

In June 2008, CESC won the Golden Ant Award of State Golden Card Project (Award for best supporting industries)

In October 2008, CESC was awarded the Second Session’s Group Member Medal issued by Changping District Charity Association in Beijing.

In December 2008, CESC was awarded Olympic Security Collective Rewards Certificate.

In January 2009, CESC was awarded Outstanding Contribution Certificate in the earthquake relief and Olympic Games.

In January 2009, CESC was granted 2008 Safety Demonstration Unit title.

In June 2009, CESC won the 2009 Golden Ant Award of State Golden Card Project (Award for innovation).

In July 2009, CESC became member of Beijing Zhongguancun Enterprise Credit Promotion Association.

In December 2009, CESC became innovative pilot enterprise of Zhongguancun National Innovation Demonstration Zone.

In December 2009, CESC won the Outstanding Enterprise Award on Innovation of Science and Technology.

In March 2010, CESC obtained the “Chip” trophy for its participation in the work of the national collective change of the second generation citizen ID card.

In May 2010, CESC was awarded 2009 Innovative Enterprise Prize on RFID product.

In June 2010, CESC was awarded May 4th Red Flag League Branch certificate issued by China Electronics Corporation.

In June 2010, CESC won 2010 Golden Ant Award of State Golden Card Project (Award for best supporting industries).

In August 2010, CESC obtained thankfulness medal issued by China Red Cross.

In February 2011, CESC obtained 2010 Best Supplier Trophy.

In May 2011, CESC won the first place award of 2010 China contactless IC card module market.

In June 2011, CESC won 2011 Golden Ant Award of State Golden Card Project (Award for best supporting industries).

In June 2011, CESC got the reputation of Advanced Communist Party Branch.

In October 2011, CESC obtained the donation certificate issued by Xidian University.

In December 2011, CESC obtained 2011 Beijing Advanced Unit Medal on inner security Work.

In December 2011, CESC was granted the title of standardization-meet enterprise on safe production of industrial enterprise in Changping district.

In May 2012, CESC won the first place award of 2011 small card market applying innovative technology in China.

In May 2012, CESC won the first place award of 2011 China contactless IC card module market.

In June 2012, CESC got the reputation of Advanced Communist Party Branch.

In June 2012, CESC won 2012 Golden Ant Award of State Golden Card Project (Award for best supporting industries).

In July 2012, CESC’s IC chip packaging equipment was granted Innovative Technology in golden card 20th anniversary.

In July 2012, CESC’s packaging process was granted Innovative Technology in golden card 20th anniversary.

In November 2012, CESC was awarded Outstanding Product Prize in 14th China international Hi-Tech Fair. (Project name: IC card module applying WLCSP process in its packaging)

In November 2012, CESC was awarded Outstanding Product Prize in 14th China international Hi-Tech Fair. (Project name: telecom card packaging in six-in-one form)

In April 2013, CESC obtained thankfulness medal granted by China Red Cross.

In June 2013, CESC won 2013 Golden Ant Award of State Golden Card Project (Award for best supporting industries).

In June 2013, CESC won 2013 Golden Ant Award of State Golden Card Project (Award for innovative product).

In June 2013, CESC won the first place award of 2012 China contactless IC card module market.

In June 2013, CESC won the first place award of 2012 China dual interface IC card module market.

In May 2013, CESC’s League Branch was granted the reputation of 2012 Youth Civilization of China Electronics Corporation (CEC).

In December 2013, CESC won the Second Class Prize of 2012 Scientific and Technological Progress Award (project name: electronic passport IC module packaging technology R & D)

In July 2013, CESC obtained Credit Enterprise at AAA Level certificate issued by China Electronics Financial Corporation, Ltd.

In December 2013, CESC won the Second Class Prize of Scientific and Technological Award issued by Chinese Institute of Electronics.

In March 2014, CESC won 2013 China Semiconductor Innovative Product and Technology Prize (project name: IC card applying WLCSP and FC packaging technology).

In March 2014, CESC got the reputation of 2013 Best Module Supplier.

In January 2014, CESC won the Third Class Prize of Beijing Scientific and Technological Progress Award (project name: process research on mass production of contactless IC card module).

In April 2014, CESC got the reputation of 2013 Beijing Honesty Building Enterprise.

In June 2014, CESC won 2013 Golden Ant Award of State Golden Card Project (Award for best supporting industries).

In June 2014, CESC won 2013 Golden Ant Award of State Golden Card Project (Award for innovative product).

In June 2014, CESC’s party branch got the reputation of 2014 Outstanding Basic Party Organization.

In May 2014, CESC’s League branch got the reputation of 2014 May 4th Red Flag League Branch.

In August 2014, CESC obtained 2014 Red Cross Humanity Service medal.

In 2014, CESC won the Third Class Prize of Scientific and Technologic Progress (project name: research and application of security technology of smart card personalization)

In March 2015, CESC obtained the Ninth (2014) China Semiconductor Innovative Product and Technology Certificate (six-in-one card packaging technology).

In March 2015, CESC obtained the Ninth (2015) China Semiconductor Innovative Product and Technology Medal (six-in-one card packaging technology).

In March 2015, CESC obtained the first place certificate in 2014 China contactless IC card module market.

In March 2015, CESC obtained the first place certificate in 2015 China dual interface IC card module market.

In December 2014, CESC won the Third Class Prize of Scientific and Technologic Award issued by Chinese Institute of Electronics (project name: development and industrialization of security technology of smart card personalization).

In June 2015, CESC won 2015 Golden Ant Award of State Golden Card Project (Award for best supporting industries).

In June 2015, CESC won 2015 Golden Ant Award of State Golden Card Project (Award for innovative product).

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| Home | Company News | Services | About us | VIP fast channel | On line message |
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|  |  | IC card package | Contact us |  |  |
|  |  | WLCSP package |  |  |  |
|  |  | Six-in-one SIM card package |  |  |  |

HR Specialist

post responsibilities:

1. in charge of specific work of HR module;

2. assist to deal with daily official work;

3. edit company regulations and rules as well as materials reported to upper company;

4. other work arranged by the leader

Qualification required:

1. education background: bachelor degree in HR related major;

2. experience and technique: with related management experience; be able to use computer and all kinds of office software proficiently; passed CET-4 examination or above with good skill in English listening, speaking, reading and writing;

3. diathesis requirements: with a strong sense of professionalism and responsibility; logical, rational good; having a team spirit and a certain degree of organization, coordination capability; with keen insight, good writing skills and language skills;

4. other requirements: good at writing and familiar with cameras preferred; with HR consulting and operating experience preferred.

Mechanical R&D engineer

post responsibilities:

1. participate in new product research and design work;

2. as to company’s R&D task arrangement, design the mechanical part and related software;

3. responsible for process design of products and improvement of equipments;

4. offer technical support and related training to all the other departments.

Qualification required:

1. education background: bachelor or above degree, at least 5 years experience in configuration design;

2. experience and technique: familiar with AutoCAD and Solidworks; having experience in large scale mechanical equipment drawing and design;

3. professional technique: familiar with knowledge of auto-control, electronics and electro-technique;

4. other requirements: with a strong sense of professionalism and responsibility; good at thinking independently and self-learning; interest in research work and smart card industry; be able to bear strong work pressure.

equipment maintenance engineer

post responsibilities:

1. complete machine care and maintenance independently to ensure the production going on smoothly;

2. assist equipment supervisor to set all kinds of records and equipment management rules;

3. edit technical documents, such as production process document, different post work instruction, etc.

Qualification required:

1. education background: bachelor degree in machinery, automation, measurement and electronics related major;

2. experience and technique: passed CET-4 examination or above; with good skill in English reading and using drafting software; understanding production management work in factory; good practical ability;

3. diathesis requirements: with a strong sense of professionalism and responsibility; good at thinking independently and self-learning; having good organization and coordination capability;

4. other requirements: be able to work on shifts.

PCB designer

post responsibilities:

1. in charge of communicate with customers; get knowledge of customers’ needs; do the feasibility study and make choice of product packaging pattern and offer solutions and suggestion to customers;

2. complete board design of different project; communicate with customers and board suppliers; ensure the design meeting needs of product and process and try to achieve the most optimal configuration in design;

3. in charge of PCB experiment and trial production and modify the design accordingly;

4. in charge of production project tracking; communicate and solve problems during the production;

5. in charge of the reliability verification during new product introduction phase;

6. feedback the process of project to customers and complete the collection and filing of project documents and data;

7. assist engineer manager in evaluation and recommendation of PCB supplier.

Qualification required:

1. college degree or above in electronics packaging engineer, electrical and electronics, signal engineer, microelectronics related major; 1 year experience in related work;

2. familiar with PCB manufacturing and packaging process; familiar with PCB related design rules; having experience in LGA packaging, QFN packaging, PCB design and layout preferred;

3. use PCB design software proficiently, such as Cadence, profile, etc.